

# PATENT ABSTRACTS OF JAPAN

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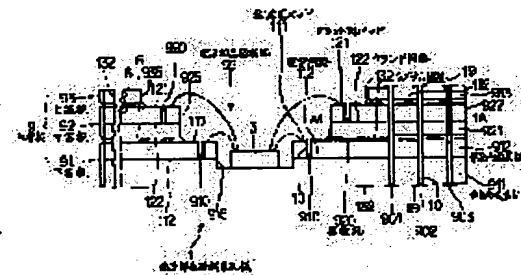
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## (54) SUBSTRATE FOR MOUNTING ELECTRONIC PARTS AND ITS MANUFACTURE

### (57)Abstract:

PURPOSE: To suppress the generation of noise and to reduce power consumption.

CONSTITUTION: The substrate is provided with a multilayer board 9 where a plurality of insulation substrates 911, 912, 921, and 933 are laminated and an electronic parts mounting part 95 provided at the multilayer board 9. One surface of the insulation substrates 912 and 922 is provided with a pad 111 for power supply, a pad 912 for ground a pad for signal, and a signal circuit 132 and the other surface is provided with a ground circuit 112 and a power supply circuit 122. The pad 111 for power supply is connected to the power supply circuit 112 and the pad 121 for ground is connected to the ground circuit 122 through continuity holes 910 and 920 provided through the insulating substrates 912 and 922. Each pad is provided around the electronic parts mounting part 95.



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